1c875 U.S. PTO
09/637570
08/11/00

Class	Subclass

ISSUE CLASSIFICATION

PATENT NUMBER

JC2
JC852

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
SCANNED Am Q.A. HT	

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/637570	F	438		2812	Nguyen, Ha

APPLICANTS
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TITLE
Polishing method, metallization fabrication method, method for manufacturing semiconductor device and semiconductor device

PTO-2040
12/99

ISSUING CLASSIFICATION

ORIGINAL		CROSS REFERENCE(S)	
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)
INTERNATIONAL CLASSIFICATION			
			☐ Continued on Issue Slip Inside File Jacket

☐ TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
☐ The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
☐ The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____				ISSUE FEE	
				Amount Due	Date Paid
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(Assistant Examiner) (Date)
(Primary Examiner) (Date)
(Legal Instruments Examiner) (Date)

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